

## MOS FIELD EFFECT TRANSISTOR $\mu$ PA1812

### P-CHANNEL MOS FIELD EFFECT TRANSISTOR FOR SWITCHING

#### **DESCRIPTION**

The  $\mu$ PA1812 is a switching device which can be driven directly by a 4.0-V power source.

The  $\mu$ PA1812 features a low on-state resistance and excellent switching characteristics, and is suitable for applications such as power switch of portable machine and so on.

#### **FEATURES**

- Can be driven by a 4.0-V power source
- · Low on-state resistance

 $R_{DS(on)1} = 39 \text{ m}\Omega$  MAX. (Vgs = -10 V, ID = -2.5 A)

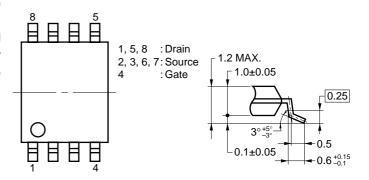
RDS(on)2 = 63 m $\Omega$  MAX. (VGS = -4.5 V, ID = -2.5 A)

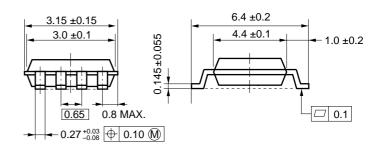
 $R_{DS(on)3} = 69 \text{ m}\Omega \text{ MAX.}$  (Vgs = -4.0 V, ID = -2.5 A)

#### ORDERING INFORMATION

PART NUMBER	PACKAGE
μPA1812GR-9JG	Power TSSOP8

#### PACKAGE DRAWING (Unit: mm)

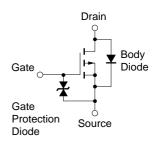




#### ABSOLUTE MAXIMUM RATINGS (TA = 25°C)

Drain to Source Voltage	VDSS	-30	V
Gate to Source Voltage	Vgss	-20/+5	V
Drain Current (DC)	ID(DC)	±5.0	Α
Drain Current (pulse) Note1	D(pulse)	±20	Α
otal Power Dissipation Note2		2.0	W
Channel Temperature	$T_ch$	150	°C
Storage Temperature	Tstg	-55 to +150	°C

#### **EQUIVALENT CIRCUIT**



- **Notes 1.** PW  $\leq$  10  $\mu$ s, Duty Cycle  $\leq$  1%
  - 2. Mounted on ceramic substrate of 5000 mm<sup>2</sup> x 1.1 mm

#### Remark

The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

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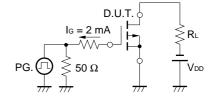
#### **ELECTRICAL CHARACTERISTICS (TA = 25°C)**

CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Zero Gate Voltage Drain Current	Ipss	V <sub>DS</sub> = -30 V, V <sub>GS</sub> = 0 V			-10	μΑ
Gate Leakage Current	lgss	Vgs = ±20 V, Vps = 0 V			±10	μΑ
Gate Cut-off Voltage	V <sub>GS(off)</sub>	$V_{DS} = -10 \text{ V}, I_{D} = -1 \text{ mA}$	-1.0	-1.6	-2.5	V
Forward Transfer Admittance	yfs	V <sub>DS</sub> = -10 V, I <sub>D</sub> = -2.5 A	1	8		S
Drain to Source On-state Resistance	RDS(on)1	V <sub>G</sub> S = -10 V, I <sub>D</sub> = -2.5 A		29	39	mΩ
	RDS(on)2	Vgs = -4.5 V, ID = -2.5 A		46	63	mΩ
	RDS(on)3	V <sub>G</sub> S = -4.0 V, I <sub>D</sub> = -2.5 A		52	69	mΩ
Input Capacitance	Ciss	V <sub>DS</sub> = −10 V		1500		pF
Output Capacitance	Coss	Vgs = 0 V		550		pF
Reverse Transfer Capacitance	Crss	f = 1 MHz		270		pF
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> = -10 V		30		ns
Rise Time	tr	I <sub>D</sub> = -2.5 A		160		ns
Turn-off Delay Time	td(off)	$V_{GS(on)} = -10 \text{ V}$		110		ns
Fall Time	tr	$R_G = 10 \Omega$		80		ns
Total Gate Charge	Q <sub>G</sub>	V <sub>DS</sub> = -24 V		31		nC
Gate to Source Charge	Qgs	I <sub>D</sub> = -5.0 A		4		nC
Gate to Drain Charge	Q <sub>GD</sub>	V <sub>G</sub> S = −10 V		8		nC
Diode Forward Voltage	V <sub>F(S-D)</sub>	IF = 5.0 A, VGS = 0 V		0.76		V

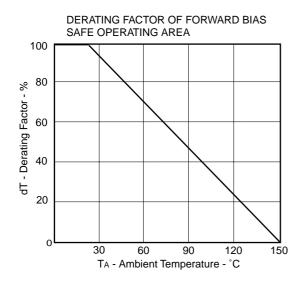
#### **TEST CIRCUIT 1 SWITCHING TIME**

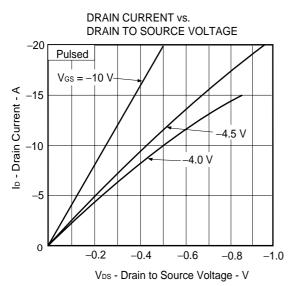
# PG. $\bigcap_{RG} R_G = 10 \ \Omega$ $\tau = 1 \mu \text{ s}$ Duty Cycle $\leq 1 \%$

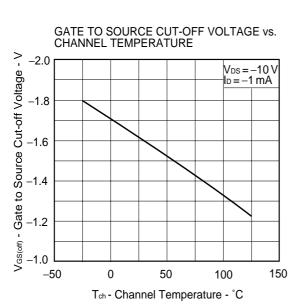
#### **TEST CIRCUIT 2 GATE CHARGE**

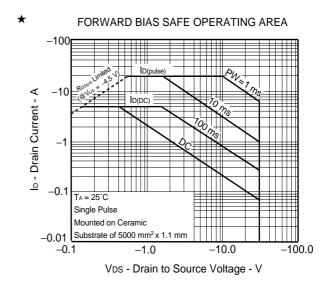


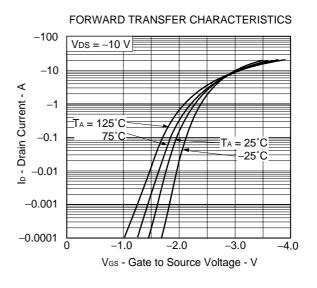
#### TYPICAL CHARACTERISTICS (TA = 25°C)

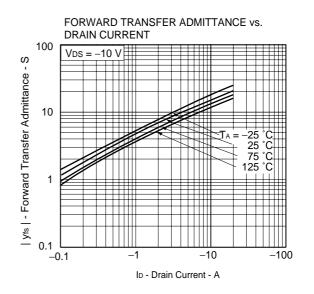




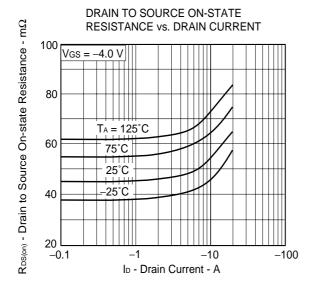


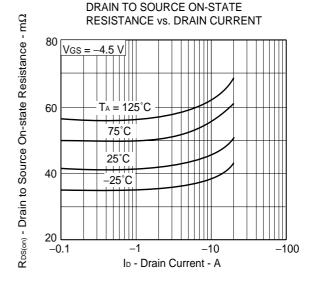


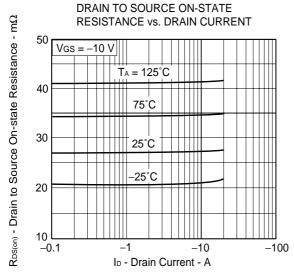


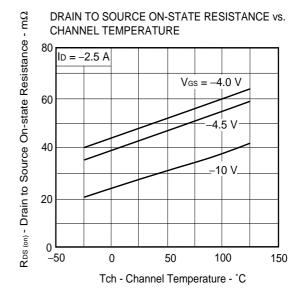


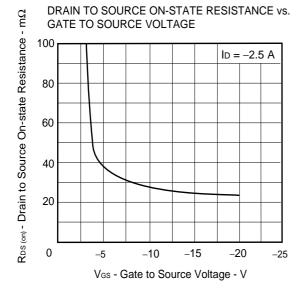
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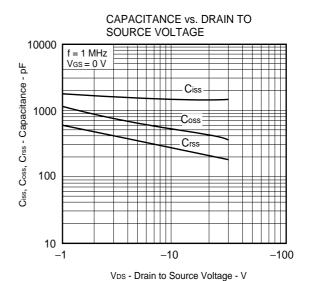


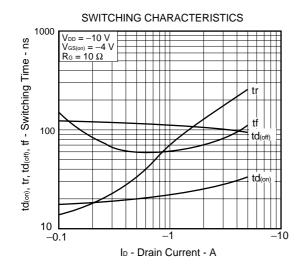


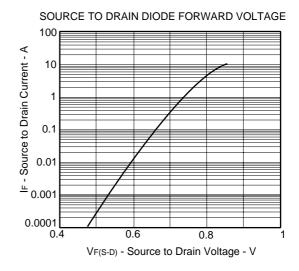


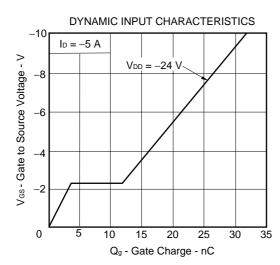


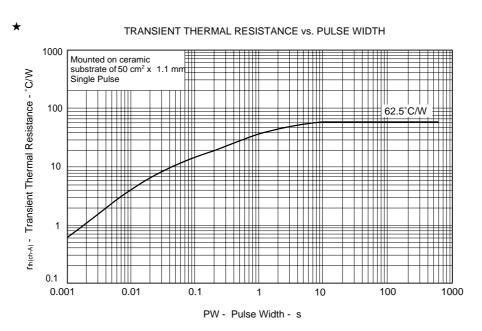












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NEC  $\mu$ PA1812

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